SN54ABT16245A, SN74ABT16245A 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SN54ABT16245A . . . WD PACKAGE

SN74ABT16245A...DGG, DGV, OR DL PACKAGE

(TOP VIEW)

SCBS300E - MARCH 1994 - REVISED MARCH 1999

48 10E

47 1 1A1

34 GND

33 2A3

32 2A4

25 20E

- **Members of the Texas Instruments** *Widebus* ™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Thin Very Small-Outline (DGV), Shrink Small-Outline (DL), and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic (WD) Flat Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16245A devices are 16-bit noninverting 3-state transceivers designed for synchronous

1B2 🛮 3 46 1 1A2 GND 4 45 GND 1B3 🛮 5 44 1 1A3 1B4 **[**] 6 43 1A4 V_{CC} [] 7 42 V_{CC} 41 1 1A5 1B5 🛮 8 1B6 📙 9 40 1A6 GND 🛮 10 39 GND 1B7 11 38 🛮 1A7 1B8 | 12 37 L 1A8 2B1 13 36 2A1 2B2 🛚 35 2A2 14

GND 15

2B3 16

2B4 🛮 17

2DIR

24

1DIR 🛮

1B1 🛮 2

31 V_{CC} V_{CC} 18 2B5 19 30 2A5 2B6 20 29 2A6 GND 21 28 GND 2B7 🛮 22 27 2A7 23 26 2A8 2B8

two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\sf OE}$ should be tied to $V_{\sf CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16245A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16245A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

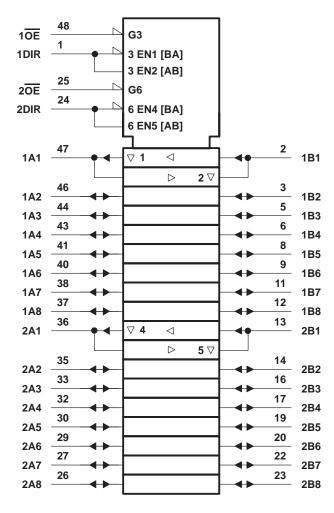


SCBS300E - MARCH 1994 - REVISED MARCH 1999

FUNCTION TABLE (each 8-bit section)

INP	UTS	ODEDATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

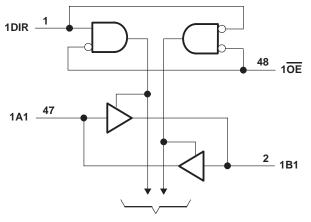
logic symbol†

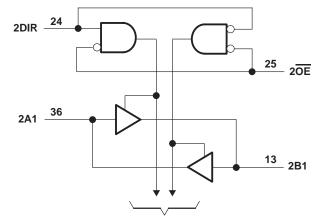


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





To Seven Other Channels To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.	5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	V to 5.5 V
Current into any output in the low state, IO: SN54ABT16245A	96 mA
SN74ABT16245A	. 128 mA
Input clamp current, I_{IK} ($V_I < 0$)	. –18 mA
Output clamp current, I _{OK} (V _O < 0)	50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	. 89°C/W
DGV package	. 93°C/W
DL package	. 94°C/W
Storage temperature range, T _{stq} 65°C	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

			SN54ABT	16245A	SN74ABT	16245A	UNIT
			MIN	MAX	MIN	MAX	UNII
Vсс	Supply voltage				4.5	5.5	V
VIH	High-level input voltage	2		2		V	
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage			Vcc	0	Vcc	V
ІОН	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51.

SN54ABT16245A, SN74ABT16245A **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCBS300E - MARCH 1994 - REVISED MARCH 1999

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAM		TEST CONDITIONS		T _A = 25°C		SN54ABT16245A		SN74ABT16245A		UNIT	
		IEST CON	DITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	I _{OH} = -3 mA	2.5			2.5		2.5		
V		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
C	Control nputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V, V}_{I}$	= V _{CC} or GND			±1		±1		±1	
II A	or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_I = V_{CC} \text{ or GND}$	V,			±20*		±100		±20	μΑ
lozpu		$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{OE} = X$				±50**		±50**		±50	μΑ
I _{OZPD}		$V_{CC} = 2.1 \text{ V to 0},$ $V_{O} = 0.5 \text{ V to 2.7 V},$	OE = X			±50**		±50**		±50	μΑ
I _{OZH} ‡		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$	V, V			10§		10		10§	μΑ
I _{OZL} ‡		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_{O} = 0.5 \text{ V}, \overline{OE} \ge 2 \text{ V}$	V, V			-10§		-10		-10§	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO¶		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V _{CC} = 5.5 V,	Outputs high			2		2		2	
ICC A	or B ports	$I_{O} = 0$,	Outputs low			32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
	loto innuto	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			2		1.5		2	
ΔICC [#] Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		1		0.05	mA	
	Control nputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	
C: -	Control nputs	V _I = 2.5 V or 0.5 V			3						pF
C _O A	or B ports	V _O = 2.5 V or 0.5 V			6						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

 $^{^\}dagger$ All typical values are at VCC = 5 V. ‡ The parameters IOZH and IOZL include the input leakage current.

[§] This limit may vary among suppliers.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $^{^{\#}}$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V $_{
m CC}$ or GND.

SN54ABT16245A, SN74ABT16245A 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS300E - MARCH 1994 - REVISED MARCH 1999

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

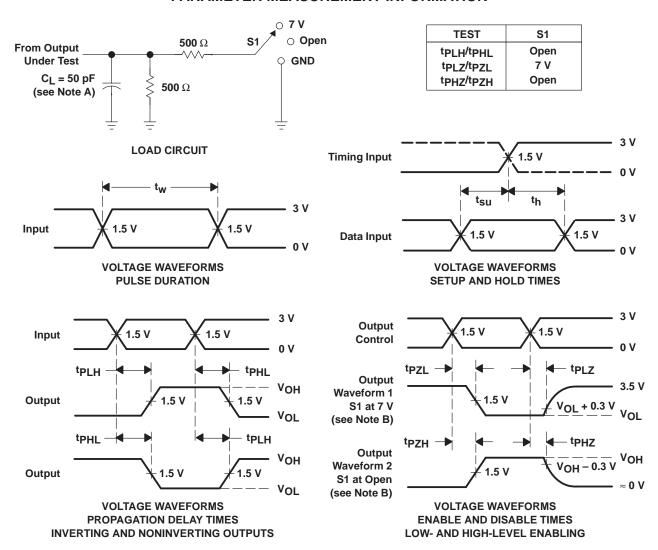
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, }	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	0.5	2.2	3.4	0.5	4	ns
^t PHL	AOID	BULK	0.5	2.3	3.8	0.5	4.6	115
^t PZH	OE	B or A	0.8	3.6	5.2	0.8	5.5	ns
t _{PZL}	OE	BULK	0.9	3.7	6.1	0.1	7.3	115
^t PHZ	ŌĒ	B or A	1.3	4.4	5.8	1.3	6.3	ns
^t PLZ	OE .	BULK	1.4	3.3	4.7	1.4	5.3	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	CC = 5 V 4 = 25°C	/, }	MIN	MAX	UNIT
		Ī	MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.4	1	3.9 ns	
t _{PHL}	AUID	B OI A	1	2.3	3.7	1	4.2	115
^t PZH	ŌĒ	B or A	1	3.6	5.2	1	6.3	nc
t _{PZL}	OE OE	D OI A	1	3.7	5.4	1	6.4	ns
^t PHZ	OE	B or A	2	4.4	5.8	2	6.3	ns
tPLZ) UE	BUIA	1.5	3.3	4.7	1.5	5.2	115

SCBS300E - MARCH 1994 - REVISED MARCH 1999

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







i.com 28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9317501MXA	ACTIVE	CFP	WD	48	1	None	Call TI	Level-NC-NC-NC
SN74ABT16245ADGGR	ACTIVE	TSSOP	DGG	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ABT16245ADGVR	ACTIVE	TVSOP	DGV	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ABT16245ADL	ACTIVE	SSOP	DL	48	25	None	CU NIPDAU	Level-1-235C-UNLIM
SN74ABT16245ADLR	ACTIVE	SSOP	DL	48	1000	None	CU NIPDAU	Level-1-235C-UNLIM
SNJ54ABT16245AWD	ACTIVE	CFP	WD	48	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.